TOP VIEW

BOTTOM VIEW

PIN 1 I.D.

SEE DETAIL 'A'

11° – 13°

.20 MIN.

GAGE PLANE

0° – 7°

1.00 REF.

LEAD FINISH: Solder Plate

BOTTOM VIEW

SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A			1.60
A₁	0.05	0.10	0.15
A₂	1.35	1.40	1.45
D/E	26.00 BSC		
D₁/E₁	24.00 BSC		
b	0.17	0.22	0.27
c	0.09		0.20
e	0.50 BSC		
L	0.45	0.60	0.75
ccc			0.08
ddd			0.08
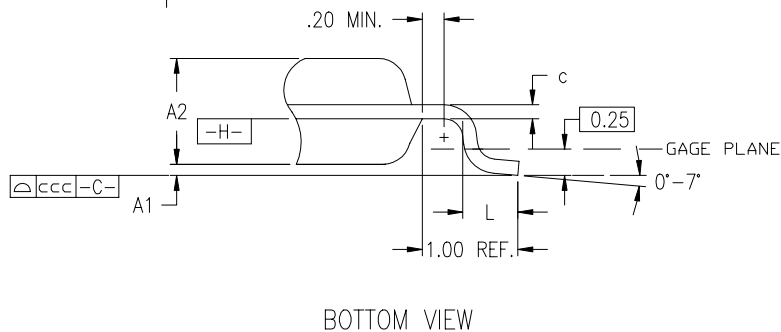
NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M–1982.

2. DIMENSIONS "D1" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED 0.25mm ON EACH SIDE.

3. THE TOP OF PACKAGE MAYBE SMALLER THAN THE BOTTOM OF PACKAGE BY 0.10mm.

4. THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MS–026.

5. MARK ORIENTATION WITH RESPECT TO PIN-1 I.D. IF 2 OR MORE CIRCLES EXIST ON TOP OF THE PACKAGE, USE THE SMALLEST CIRCLE AS PIN-1 I.D.

160–PIN TQFP (TQ160)